

Y
(Lochbild)
(board drillings)

alle Löcher
all holes

$\varnothing 0,05$

$\varnothing 1 \pm 0,1$

Position
position

10

1

c
b
a
Reihe
row

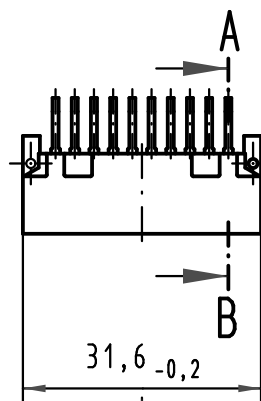
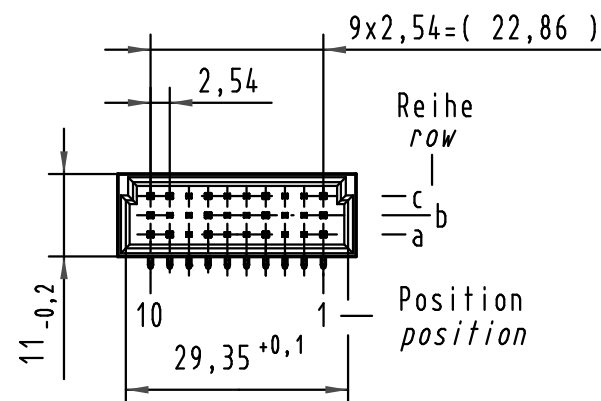
2x 2,54 (=5,08)

2,54

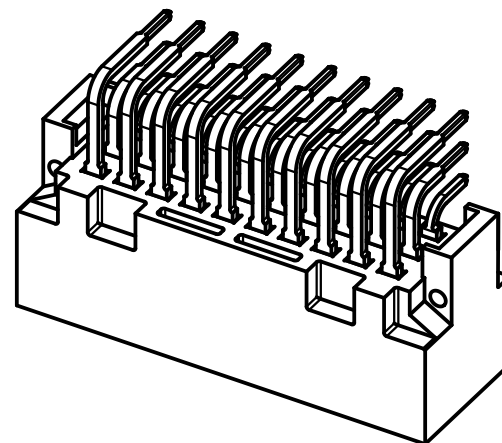
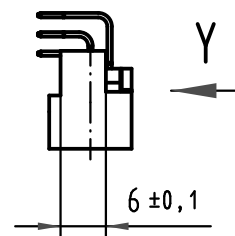
5,3 $\pm 0,1$

9x 2,54 (=22,86)

2,54



Z



A-B
2:1

X Kontaktbelegung
contact loading

3,85 $\pm 0,2$
 $-0,05$

3 $-0,4$

2x 2,54 (=5,08)

2,54

6,24

2,54

8,7 $\pm 0,1$

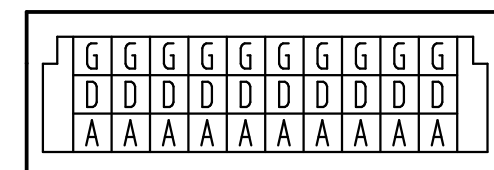
6,4 $-0,1$

4,8 $\pm 0,2$

A D G — Kontakt-Typ
pin-type
Standard
standard pin

B E H —
Voreiler
preleading pin 0,8 mm

Referenzebene Tiefe
datum plane depth

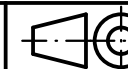
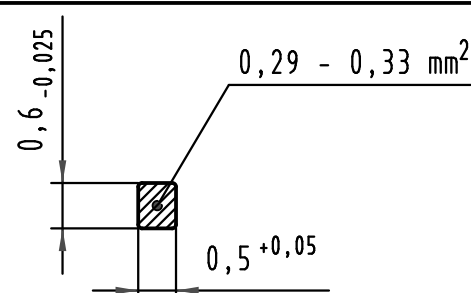


10 | 8 | 6 | 4 | 2 |
9 | 7 | 5 | 3 | 1

09 25 130 6579	2	Au flash over PdNi over Ni
Bestell-Nr. part-no.	Anforderungsstufe nach IEC performance level acc. to IEC	Kontaktoberfläche contact plating

Z
10:1

Querschnitt der
Lötanschlüsse:
cross-section of
solder terminations:



All Dimensions in mm
Original Size DIN A 3

Techn. Character.

	Dat.	Name	Maßstab/Scale
Detail.	05.05.09	MR	1:1
Insp.	05.05.09	RA	2:1
Stand.			10:1

Nicht tolerierte Maße/Free size tolerances
IEC 60603-2

Bauform 3C Messerleiste ohne Flansch
Einlöt , 30 pol., SMC (Hochtemperatur)
type 3C male connector without flange
solder , 30 pol., SMC (high temperature)

35605		
Mod.	Dat.	Name

HARTING Electronics GmbH & Co. KG
D-32339 ESPELKAMP



TB 09 25 130 x579	Blatt/ page
Sub.	